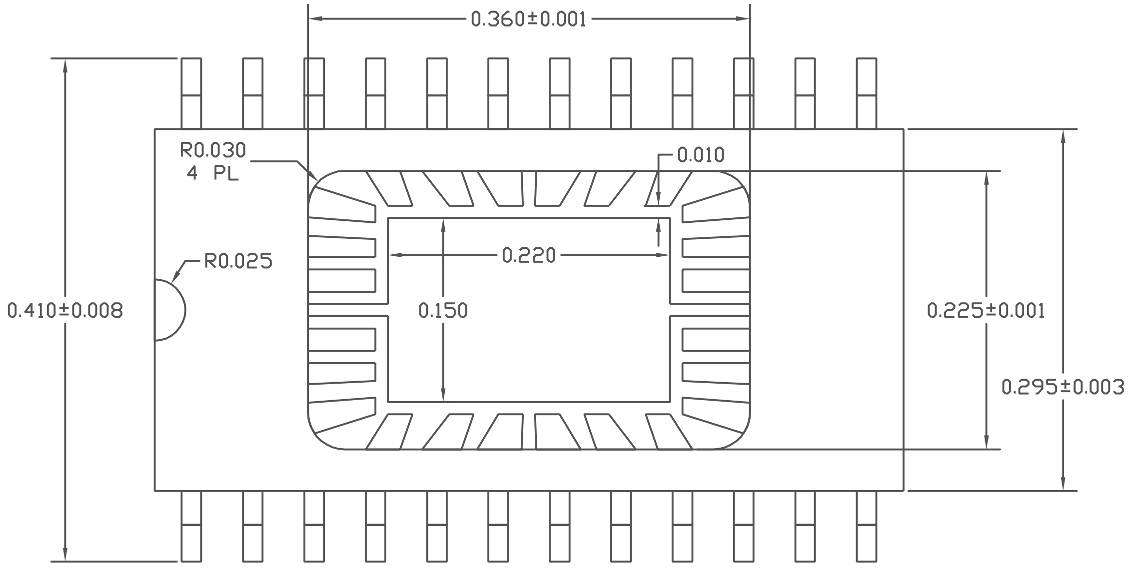
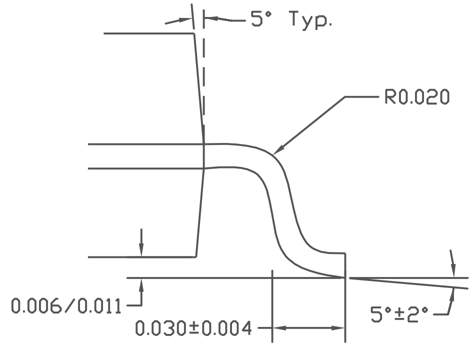
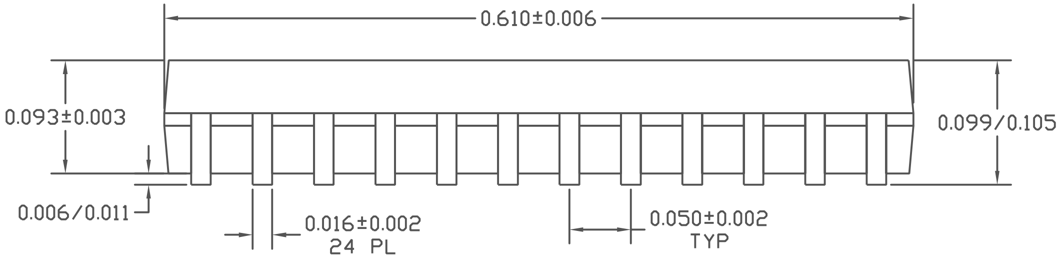
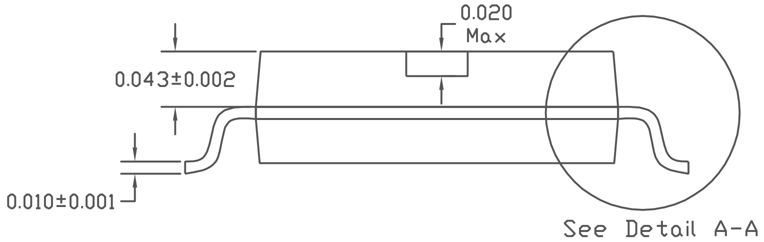
ECN	REV.	DESCRIPTION	DATE:	APP'D:
10006	-	INITIAL RELEASE	01/31/01	BF



DETAIL A-A







NOTES:
BODY : PLASTIC, SEMICONDUCTOR GRADE
LEAD FRAME : COPPER, OLIN 194
LEAD FINISH : 50 uIN Au, OVER 50 uIN Ni
DIE PAD : 0.220" x 0.150"

SPECTRUM
SEMICONDUCTOR MATERIALS, INC.

TITLE:
24 LEAD SOIC OPEN-PAK (Tooling Outline)

MATERIAL: SEE NOTES	SCALE: NONE	DRAWN BY: S.O.
GEN. TOL.: ±.005	DATE: 12/10/00	APP'D: BF 01/31/01

SSM P/N: PSO243001	DWG. NO.: SOIC24-OP-01-T	REV. -